

ZX2200 High Precision Die Bonder



Cleansem Sdn Bhd (319007-A)

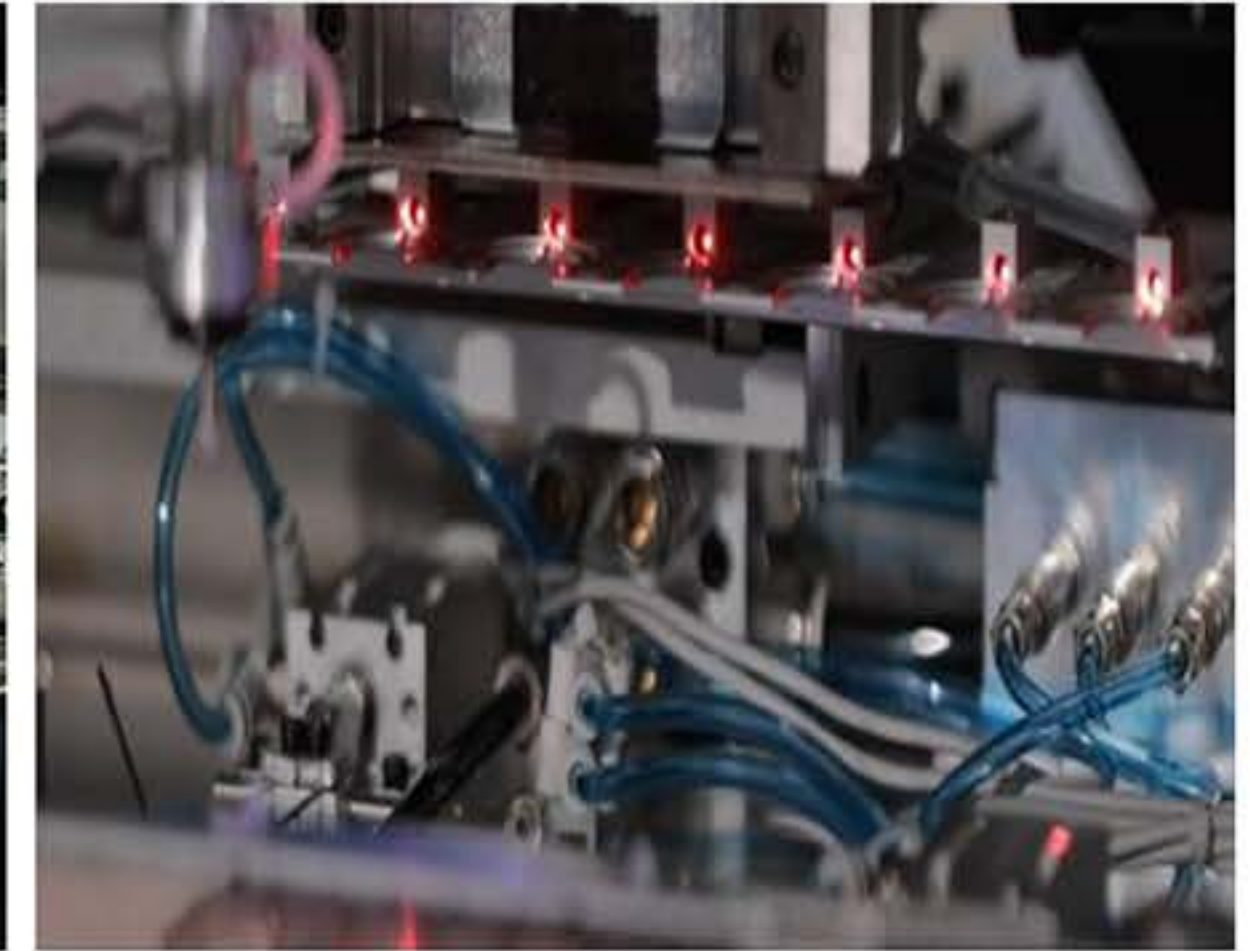
Accuracy SiP Module Multi-Chip



Placement Accuracy +/- 10 um



Wafer Handling up to 300mm



7 Pick up tools



Waffle/Gel Pack/ Chip Tray



Auto Dispensing Sys



5 x Die Ejector